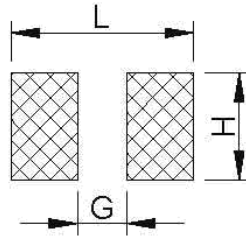


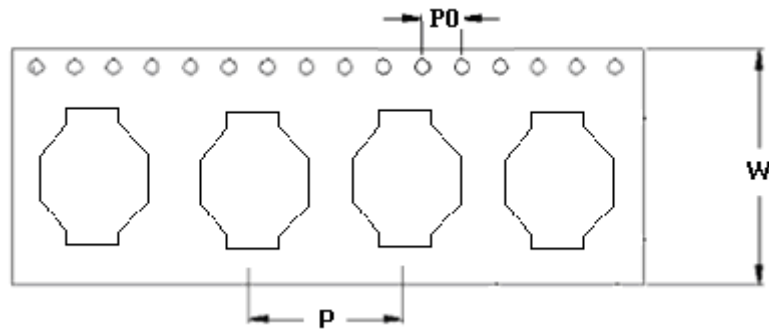
SPECIFICATION FOR APPROVAL

PAD LAYOUT: (UNIT: mm)



ITEM	L (Ref.)	G (Ref.)	H (Ref.)
BS1813	8.89	5.08	4.06
BS3308	11.68	8.68	4.06
BS3316	11.68	8.68	4.06
BS3340	11.68	8.68	4.06
BS5022	20.71	14.35	8.64

PACKAGING QUANTITY: (UNIT: mm)



TYPE	P	P0	W	BULK	PCS / REEL
BS1813	12.0 ± 0.1	4.0 ± 0.1	16.0 ± 0.3	v	1000
BS3308	16.0 ± 0.1	4.0 ± 0.1	24.0 ± 0.3	v	1000
BS3316	16.0 ± 0.1	4.0 ± 0.1	24.0 ± 0.3	v	500
BS3340	16.0 ± 0.1	4.0 ± 0.1	24.0 ± 0.3	v	250
BS5022	20.0 ± 0.1	4.0 ± 0.1	32.0 ± 0.3	v	500

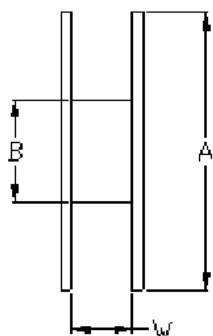
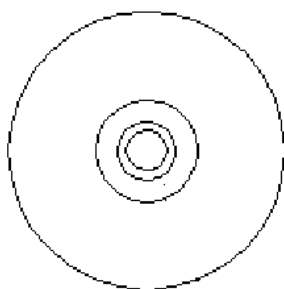


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SPECIFICATION FOR APPROVAL

PACKAGING QUANTITY: (UNIT: mm)



TYPE	A	B	W
BS3308	330	100	24.5
BS3316	330	100	24.5
BS3340	330	100	24.5
BS5022	330	100	32.5
BS1813	330	100	16.5

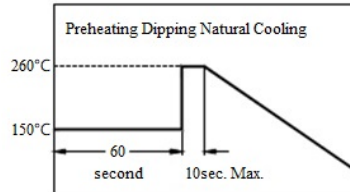


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SPECIFICATION FOR APPROVAL

RELIABILITY AND TEST CONDITIONS:

Item	Performance	Test Condition															
Operating Temperature	-40~+125℃																
Rated Current	Refer to standard electrical characteristics list.																
Temperature Rise Test	40℃ max. (Δt)																
Solder heat Resistance	Appearance: No significant abnormality. Inductance change: Within $\pm 30\%$.	Preheat: 150℃, 60sec. Solder : H63A Solder temperature: 260+0-5℃ Flux: rosin Dip time: 10sec. Max. 															
Thermal shock		Condition for 1 cycle Step1: -25 $\pm$ 2℃ 30 $\pm$ 3 min. Step2: Room temperature 15 min. Step3: +85 $\pm$ 5℃ 30 $\pm$ 3 min. Step4: Room temperature 15 min. Number of cycles: 50 <table border="1"> <thead> <tr> <th>Phase</th><th>Temperature(℃)</th><th>Time(min)</th></tr> </thead> <tbody> <tr> <td>1</td><td>-25$\pm$2℃</td><td>30$\pm$3</td></tr> <tr> <td>2</td><td>Room Temp.</td><td>15</td></tr> <tr> <td>3</td><td>+85$\pm$2℃</td><td>30$\pm$3</td></tr> <tr> <td>4</td><td>Room Temp.</td><td>15</td></tr> </tbody> </table>	Phase	Temperature(℃)	Time(min)	1	-25 $\pm$ 2℃	30 $\pm$ 3	2	Room Temp.	15	3	+85 $\pm$ 2℃	30 $\pm$ 3	4	Room Temp.	15
Phase	Temperature(℃)	Time(min)															
1	-25 $\pm$ 2℃	30 $\pm$ 3															
2	Room Temp.	15															
3	+85 $\pm$ 2℃	30 $\pm$ 3															
4	Room Temp.	15															
Humidity Resistance Test	Appearance: no damage Inductance: within $\pm 30\%$ of initial value.	Measured: 50 times Temperature: 40 $\pm$ 2℃. Applied current: rated current. Duration: 500 hrs. Humidity: 90~95%															
High Temperature Resistance Test		Temperature: 85 $\pm$ 2℃. Applied current: rated current. Duration: 500 hrs.															



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